

**Expert in Equipment, Products and Services for Electronics**

## VAPOR PHASE REFLOW SOLDERING VS-500-V



The upgrades since the VS-500-IV,

- A high efficiency chiller included
- It can go up to 10 temperature levels
- ESD paint
- ESD top glass
- Display of the real-time reflow profile integrated into the machine
- Light signal column

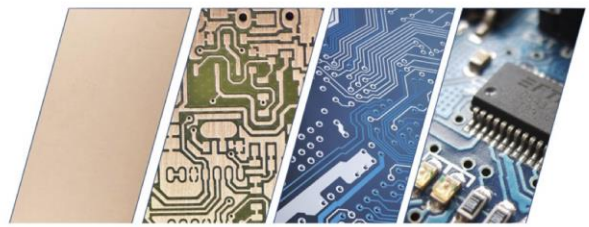
The design of the machine allows to solder even the most complex cards with a format of max. **500 x 500 x 60 mm** while ensuring optimal quality thanks to,

- The inert atmosphere resulting from the fluid (medium) used
- An incomparable temperature delta across the entire component
- No possible handling error during the cycle

The main applications relate to lead and lead-free soldering, conductive adhesives and repair.

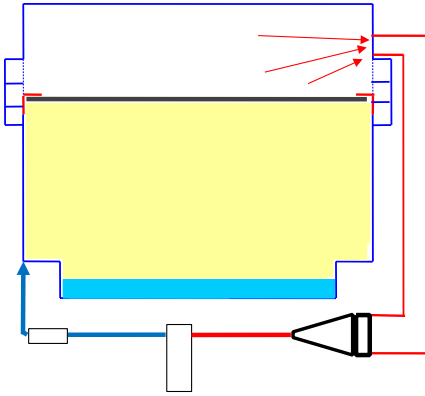
The concept of the **CIF** vapor phase soldering allows today,

- Reducing fluid consumption (medium) using a unique vapor recovery system; this greatly reduces production costs
- Quick return on investment and high capacity for mixed productions
- Optimum soldering quality in inert atmosphere and vacuum (without void)
- Compensation for pressure fluctuations in the tank
- Minimum temperature delta throughout the working area - not achievable with other technologies
- Reduced energy consumption
- Sub-assembly repair: desoldering and resoldering
- High reliability for all types of soldering
- Precision and repeatability
- Possibility of soldering large format 500 x 500 x 60 mm cards in a small footprint



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Recover all vapor before opening the door

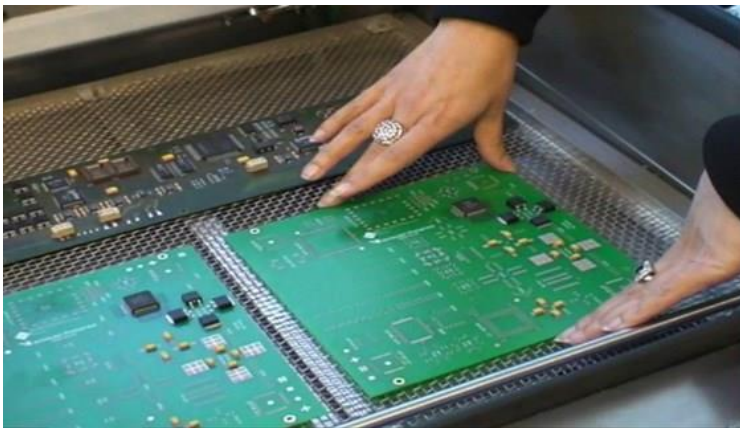


**BENEFITS**

- Massive reduction in medium consumption
- Big fume reduction
- Reduced medium smell
- Reduced cycle time
- Reduced downtime

**HIGH RETURN ON INVESTMENT !**

**ASSEMBLY**



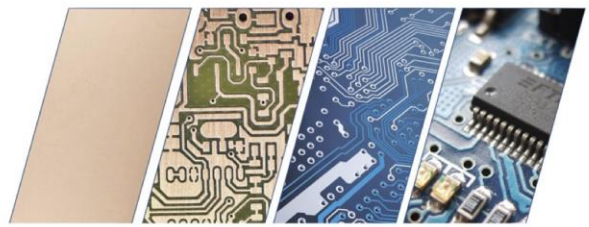
**TECHNICAL CHARACTERISTICS**

Model	<b>VS-500-V</b>
Reference	<b>V900330</b>
Max PCB dimensions	<b>500 x 500 x 60 mm</b>
Max. Load capacity	<b>2 Kg</b>
Medium capacity	<b>5 Kg</b>
Dimensions (L x W x H)	<b>830 x 775 x 1140 mm</b>
Installed power	<b>7,5 KW / H</b>
Power supply	<b>3 x 400 V + N / 50 Hz</b>

**OPTIONS AND ACCESSORIES**

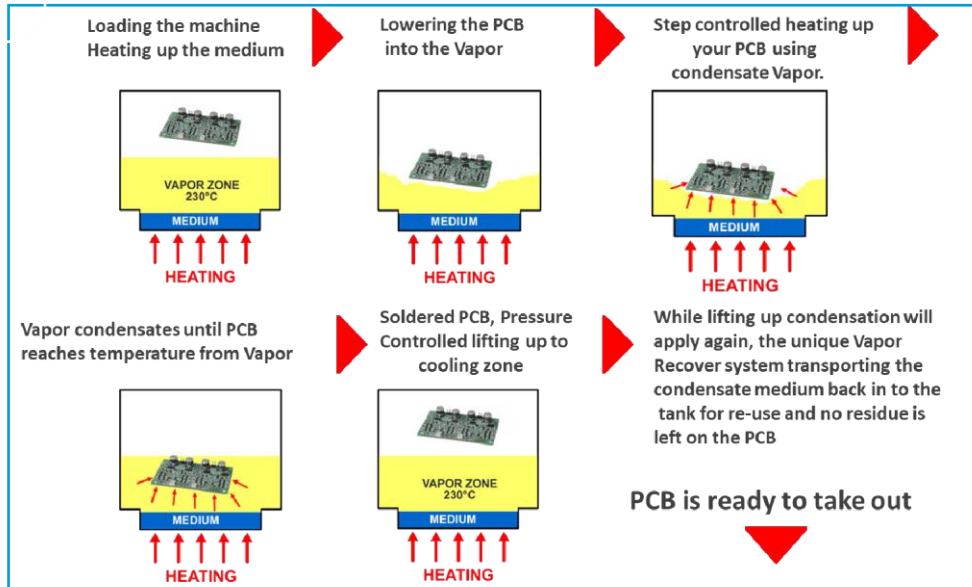
Medium (fluid) HS260 – <b>260°C</b> - 5 kg	<b>V800093</b>
Medium (fluid) HS240 – <b>240°C</b> - 5 kg	<b>V800094</b>
Medium (fluid) XS 235 – <b>235°C</b> - 5 kg	<b>V800095</b>
Medium (fluid) LS 230 – <b>230°C</b> - 5 kg	<b>V800096</b>
Medium (fluid) LS 215 – <b>215°C</b> - 5 kg	<b>V800117</b>
Medium (fluid) LS 200 – <b>200°C</b> - 5 kg	<b>V800108</b>
Universal carrier (frame) for VS-500 HD	<b>V800100</b>
AGS - Automatic Galden® setpoint detection for VS-500	<b>V800105</b>
Software update - per update with travel expenses - for VS-500	<b>V800106</b>





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**ASSEMBLY**



DISCOVER ALL OUR REFLOW OVENS CIF ON <https://cif.fr/>



Solutions for your  
prototypes and micro-series



Solutions for your  
small series and production



*Technical information data subject to change without notice, texts, photos and drawings are non-contractual.*

